

MOSFET – Power

170 mAmps, 100 Volts

N-Channel SOT-23

BSS123LT1G, BVSS123LT1G

Features

- BVSS Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|-----------|----------|------|
| Drain-Source Voltage | V_{DSS} | 100 | Vdc |
| Gate-Source Voltage | V_{GS} | ± 20 | Vdc |
| – Continuous | V_{GSM} | ± 40 | Vpk |
| – Non-repetitive ($t_p \leq 50 \mu s$) | | | |
| Drain Current | I_D | 0.17 | Adc |
| – Continuous (Note 1) | I_{DM} | 0.68 | |
| – Pulsed (Note 2) | | | |

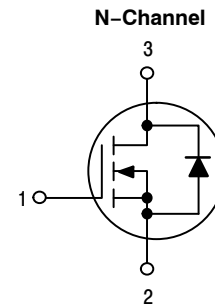
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

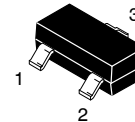
| Characteristic | Symbol | Max | Unit |
|---|-----------------|-------------|----------------------|
| Total Device Dissipation FR-5 Board (Note 3) $T_A = 25^\circ C$ Derate above $25^\circ C$ | P_D | 225 1.8 | mW mW/ $^\circ C$ |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 556 | $^\circ C/W$ |
| Junction and Storage Temperature | T_J, T_{stg} | -55 to +150 | $^\circ C$ |

1. The Power Dissipation of the package may result in a lower continuous drain current.
2. Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2.0\%$.
3. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

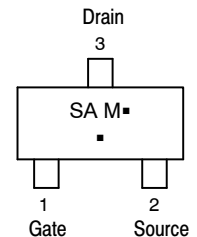
170 mAmps
100 VOLTS
 $R_{DS(on)} = 6 \Omega$



MARKING DIAGRAM & PIN ASSIGNMENT



SOT-23
CASE 318
STYLE 21



- SA = Device Code
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

BSS123LT1G, BVSS123LT1G

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|---|----------------------|-----|-----|----------|------|
| OFF CHARACTERISTICS | | | | | |
| Drain-Source Breakdown Voltage (V _{GS} = 0, I _D = 250 μAdc) | V _{(BR)DSS} | 100 | - | - | Vdc |
| Zero Gate Voltage Drain Current (V _{GS} = 0, V _{DS} = 100 Vdc) T _J = 25°C T _J = 125°C | I _{DSS} | - | - | 15 60 | μAdc |
| Gate-Body Leakage Current (V _{GS} = 20 Vdc, V _{DS} = 0) | I _{GSS} | - | - | 50 | nAdc |

ON CHARACTERISTICS (Note 4)

| | | | | | |
|--|---------------------|-----|---|-----|-------|
| Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = 1.0 mAdc) | V _{GS(th)} | 1.6 | - | 2.6 | Vdc |
| Static Drain-Source On-Resistance (V _{GS} = 10 Vdc, I _D = 100 mAdc) | r _{DS(on)} | - | - | 6.0 | Ω |
| Forward Transconductance (V _{DS} = 25 Vdc, I _D = 100 mAdc) | g _{fs} | 80 | - | - | mmhos |

DYNAMIC CHARACTERISTICS

| | | | | | |
|--|------------------|---|-----|---|----|
| Input Capacitance (V _{DS} = 25 Vdc, V _{GS} = 0, f = 1.0 MHz) | C _{iss} | - | 20 | - | pF |
| Output Capacitance (V _{DS} = 25 Vdc, V _{GS} = 0, f = 1.0 MHz) | C _{oss} | - | 9.0 | - | pF |
| Reverse Transfer Capacitance (V _{DS} = 25 Vdc, V _{GS} = 0, f = 1.0 MHz) | C _{rss} | - | 4.0 | - | pF |

SWITCHING CHARACTERISTICS⁽⁴⁾

| | | | | | | |
|---------------------|--|---------------------|---|----|---|----|
| Turn-On Delay Time | (V _{CC} = 30 Vdc, I _C = 0.28 Adc, V _{GS} = 10 Vdc, R _{GS} = 50 Ω) | t _{d(on)} | - | 20 | - | ns |
| Turn-Off Delay Time | | t _{d(off)} | - | 40 | - | ns |

REVERSE DIODE

| | | | | | |
|--|-----------------|---|---|-----|---|
| Diode Forward On-Voltage (I _D = 0.34 Adc, V _{GS} = 0 Vdc) | V _{SD} | - | - | 1.3 | V |
|--|-----------------|---|---|-----|---|

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------------|---------------------|-----------------------|
| BSS123LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| BVSS123LT1G* | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| BSS123LT7G | SOT-23 (Pb-Free) | 3,500 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*BVSS Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

BSS123LT1G, BVSS123LT1G

TYPICAL ELECTRICAL CHARACTERISTICS

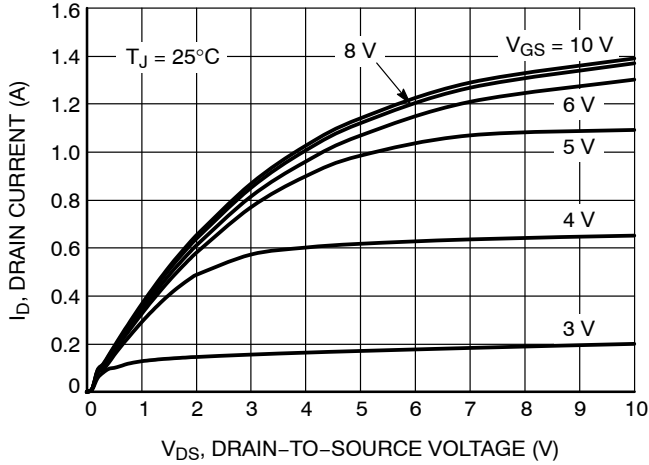


Figure 1. On-Region Characteristics

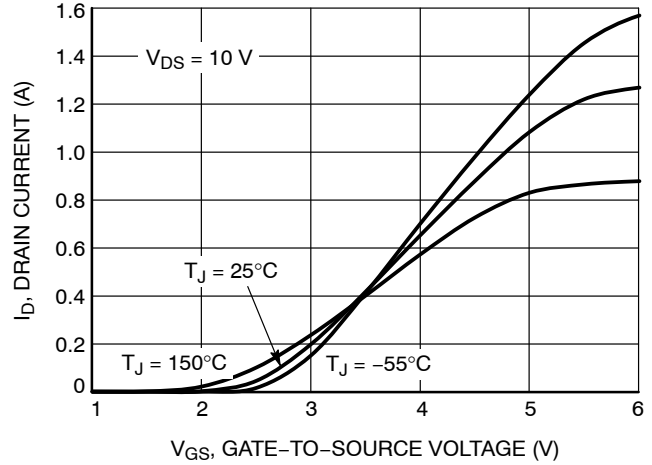


Figure 2. Transfer Characteristics

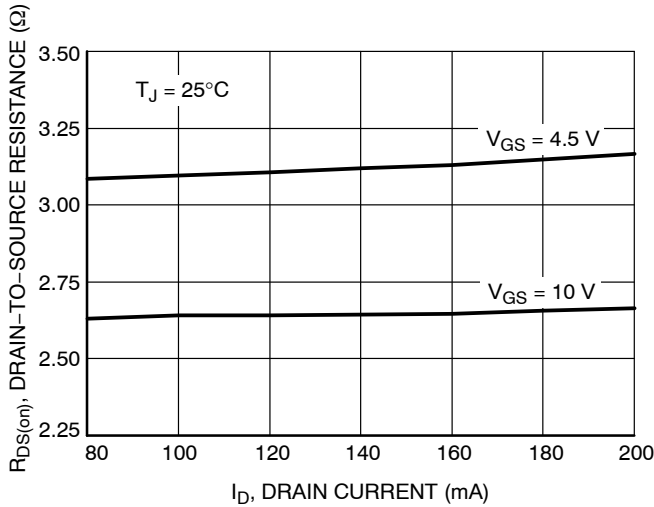


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

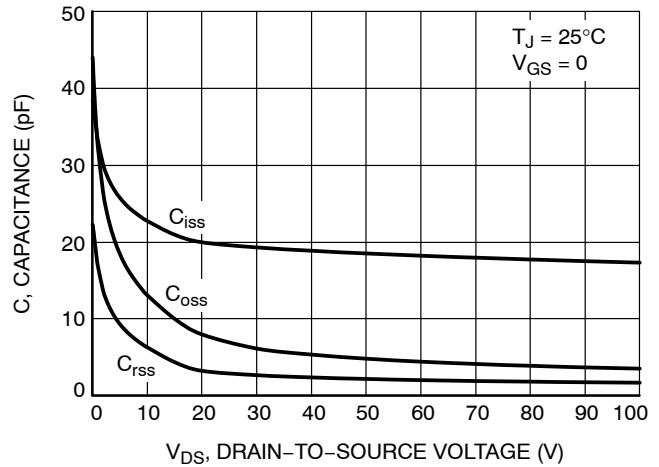


Figure 4. Capacitance Variation

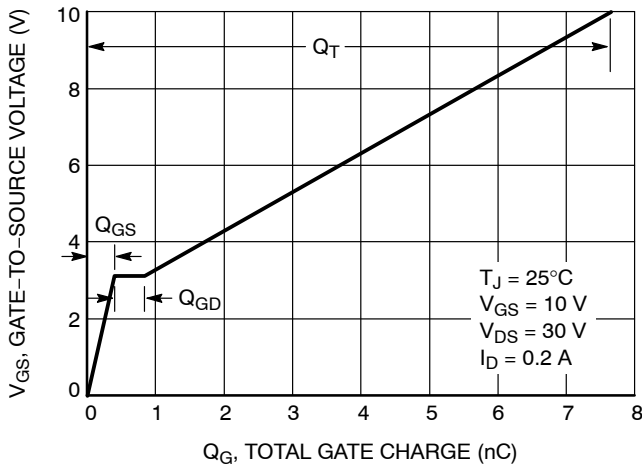


Figure 5. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

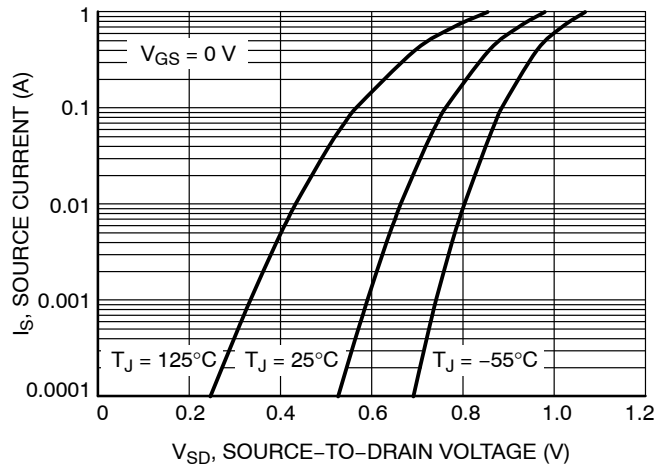


Figure 6. Diode Forward Voltage vs. Current

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TYPICAL ELECTRICAL CHARACTERISTICS

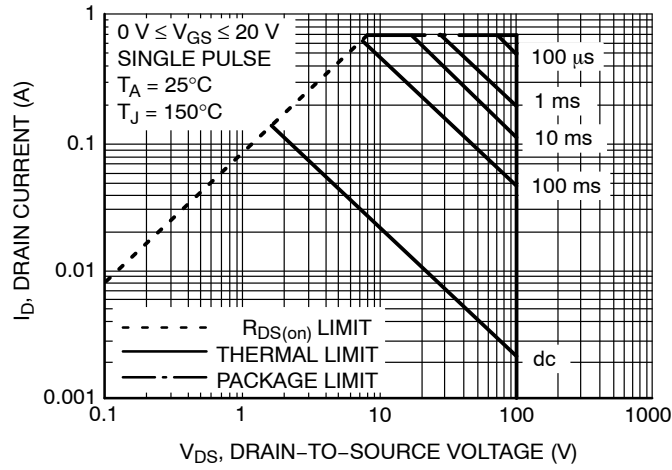


Figure 7. Maximum Rated Forward Biased Safe Operating Area

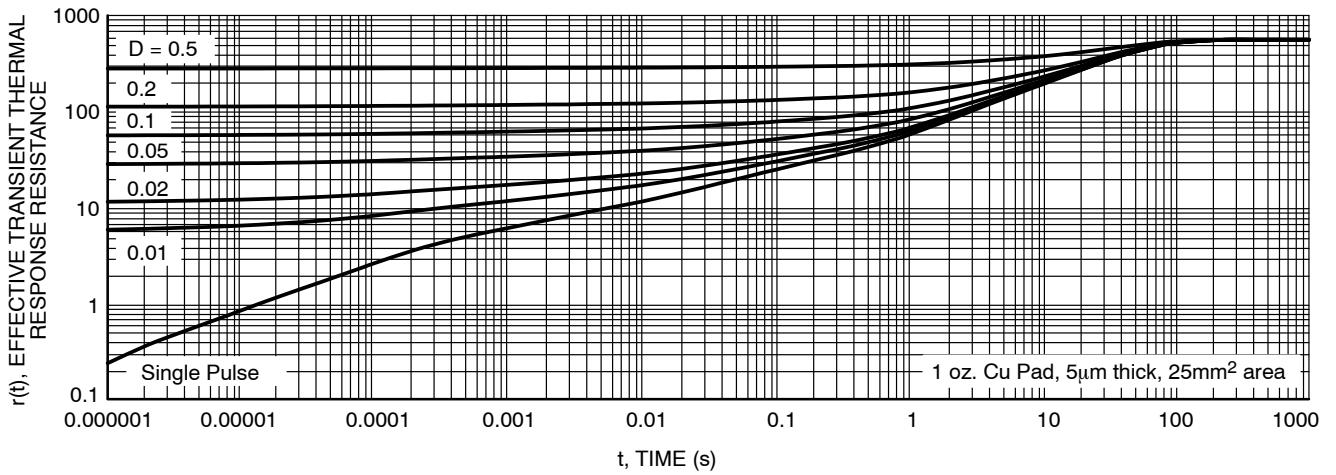


Figure 8. Thermal Response

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



SOT-23 (TO-236) CASE 318-08 ISSUE AS

DATE 30 JAN 2018

SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.89 | 1.00 | 1.11 | 0.035 | 0.039 | 0.044 |
| A1 | 0.01 | 0.06 | 0.10 | 0.000 | 0.002 | 0.004 |
| b | 0.37 | 0.44 | 0.50 | 0.015 | 0.017 | 0.020 |
| c | 0.08 | 0.14 | 0.20 | 0.003 | 0.006 | 0.008 |
| D | 2.80 | 2.90 | 3.04 | 0.110 | 0.114 | 0.120 |
| E | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| e | 1.78 | 1.90 | 2.04 | 0.070 | 0.075 | 0.080 |
| L | 0.30 | 0.43 | 0.55 | 0.012 | 0.017 | 0.022 |
| L1 | 0.35 | 0.54 | 0.69 | 0.014 | 0.021 | 0.027 |
| HE | 2.10 | 2.40 | 2.64 | 0.083 | 0.094 | 0.104 |
| T | 0° | --- | 10° | 0° | --- | 10° |

RECOMMENDED SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLE 1 THRU 5:
CANCELLED

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE

STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE

STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE-ANODE

STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE

STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE

STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE

STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE

STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE

STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE

STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE-ANODE

STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT

STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE

STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION

STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE

STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE

| | | |
|-------------------------|------------------------|--|
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